

ABSTRACT OF THE DISCLOSURE

5 A component mounting system which includes a printer for printing solder on electrodes formed on a board; a first inspection unit for detecting positions of printed solder and outputting solder position detection results; a component mounting unit for picking up components from a component feeder carriage and placing the components on the board using mounting heads; a second inspection unit for inspecting positions of the components placed and outputting component position detection results; a soldering unit for soldering the components onto the board by heating and melting solder; and a main controller for updating at least a control parameter for controlling the printer operation or a control parameter for the component mounting unit operation based on at least the solder position detection results or component position detection results. The above configuration enables the accurate and efficient quality control throughout the mounting process.

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